

SOT929-1

plastic low profile fine-pitch ball grid array package; 272 balls; body 15 x 15 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA272
Package type industry code	LFBGA272
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	21-12-2005

Table 1. Package summary

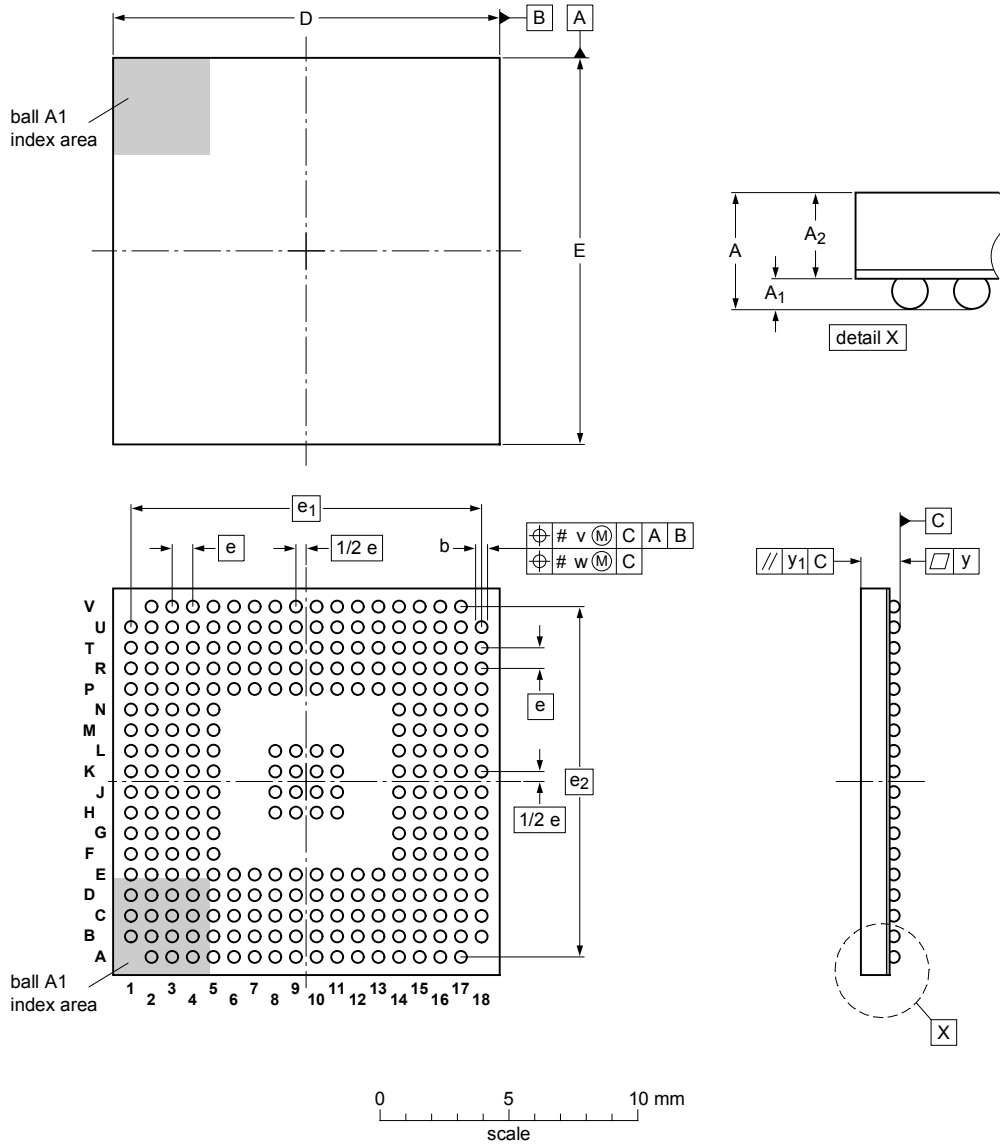
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	1.5	1.5	mm
A ₂	package height	0.95	-	1	1.1	mm
n ₂	actual quantity of termination	-	-	272	-	



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2. Package outline

LFBGA272: plastic low profile fine-pitch ball grid package; 272 balls; body 15 x 15 x 1 mm SOT929-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.5	0.4 0.3	1.10 0.95	0.5 0.4	15.1 14.9	15.1 14.9	0.8	13.6	13.6	0.15	0.08	0.12	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT929-1		MO-205				05-12-14 05-12-21

Fig. 1. Package outline LFBGA272 (SOT929-1)

3. Legal information

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